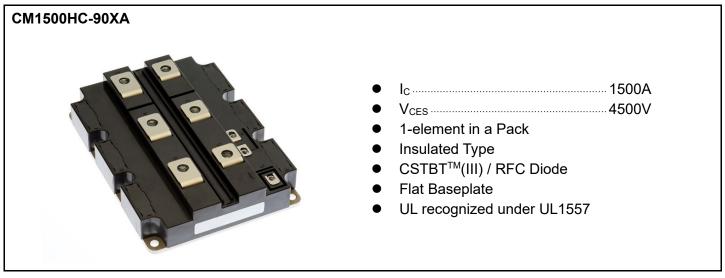


< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

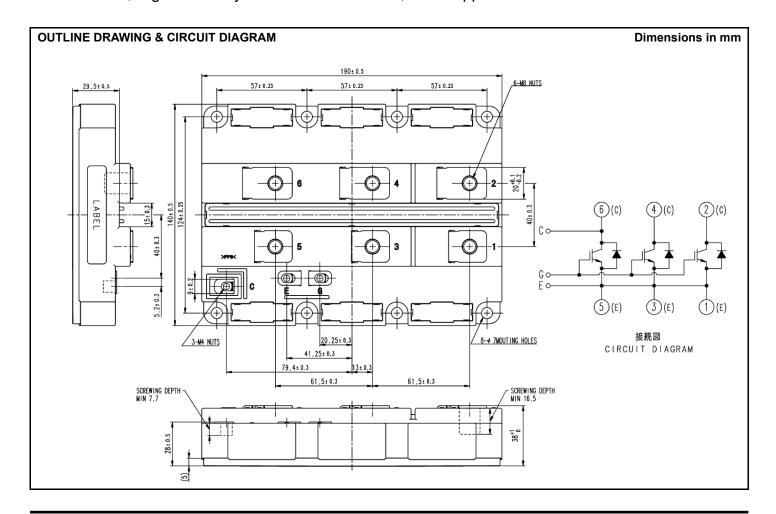
### CM1500HC-90XA

HIGH POWER SWITCHING USE INSULATED TYPE



### **APPLICATION**

Traction drives, High Reliability Converters / Inverters, DC choppers



### < High Voltage Insulated Gate Bipolar Transistor : HVIGBT >

# CM1500HC-90XA HIGH POWER SWITCHING USE INSULATED TYPE

### **MAXIMUM RATINGS**

Symbol	Item	Conditions	Ratings	Unit
V	Collector emitter veltage	V <sub>GE</sub> = 0V, T <sub>j</sub> =+25+150°C	4500	V
V <sub>CES</sub>	Collector-emitter voltage	$V_{GE} = 0V, T_j = -50^{\circ}C$	3900	V
$V_{GES}$	Gate-emitter voltage	$V_{CE} = 0V, T_j = 25^{\circ}C$	± 20	V
Ic	Collector current	DC, T <sub>c</sub> = 105°C	1500	Α
I <sub>CRM</sub>	Collector current	Pulse (Note 1)	3000	Α
IE	Emitter current (Note 2)	DC, T <sub>c</sub> = 90°C	1500	Α
I <sub>ERM</sub>	Emitter current (Note 2)	Pulse (Note 1)	3000	Α
P <sub>tot</sub>	Maximum power dissipation (Note 3)	T <sub>c</sub> = 25°C, IGBT part	14700	W
V <sub>iso</sub>	Isolation voltage	RMS, sinusoidal, f = 60Hz, t = 1 min	6000	V
Ve	Partial discharge extinction voltage	RMS, sinusoidal, f = 60Hz, Q <sub>PD</sub> ≤ 10 pC	3500	V
T <sub>j</sub>	Junction temperature		-50 ~ +150	°C
T <sub>jop</sub>	Operating junction temperature		<b>−50 ~ +150</b>	°C
T <sub>stg</sub>	Storage temperature		<b>−55 ~ +150</b>	°C
t <sub>psc</sub>	Short circuit pulse width	$V_{CC} = 3000V, V_{CE} \le V_{CES}, V_{GE} = 15V, T_j = 150^{\circ}C$	10	μS

### **ELECTRICAL CHARACTERISTICS**

Comple al	lta	Conditions			Limits		Unit
Symbol	Item			Min	Тур	Max	Unit
			T <sub>i</sub> = 25°C		_	10.0	
I <sub>CES</sub>	Collector cutoff current	$V_{CE} = V_{CES}, V_{GE} = 0V$	T <sub>i</sub> = 125°C	_	10.0	_	mA
			T <sub>j</sub> = 150°C		_	120	
V <sub>GE(th)</sub>	Gate-emitter threshold voltage	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}, T_{j} = 25^{\circ}\text{C}$		6.5	7.0	7.5	V
I <sub>GES</sub>	Gate leakage current	$V_{GE} = V_{GES}, V_{CE} = 0V, T_{j} = 25^{\circ}C$		_	_	0.5	μΑ
Cies	Input capacitance	\( - 40\\\\\ - 0\\\ f - 400\\\\		_	170	_	nF
C <sub>oes</sub>	Output capacitance	$V_{CE} = 10 \text{ V}, V_{GE} = 0 \text{ V}, f = 100 \text{ kHz}$		_	11	_	nF
C <sub>res</sub>	Reverse transfer capacitance	T <sub>j</sub> = 25°C		_	1.5	_	nF
Q <sub>G</sub>	Total gate charge	$V_{CC} = 2800V$ , $I_{C} = 1500A$ , $V_{GE} = \pm 15V$		_	12.6	_	μC
		Ic = 1500 A (Note 4)	T <sub>j</sub> = 25°C	_	2.20	_	
$V_{CEsat}$	Collector-emitter saturation voltage	.0	T <sub>i</sub> = 125°C	_	2.65	_	V
		V <sub>GE</sub> = 15 V	T <sub>j</sub> = 150°C	_	2.80	3.30	
t <sub>d(on)</sub>	Turn-on delay time		T <sub>j</sub> = 150°C	_	_	1.00	μs
t <sub>r</sub>	Rise time	V <sub>cc</sub> = 2800 V	T <sub>i</sub> = 150°C	_	_	0.50	μs
	Turn-on switching energy (Note 5) per pulse		T <sub>i</sub> = 25°C	_	_	_	
E <sub>on(10%)</sub>			T <sub>j</sub> = 125°C	_	7.20	_	J
		$R_{G(on)} = 2.4 \Omega$	T <sub>j</sub> = 150°C	_	7.50	_	
	Turn-on switching energy (Note 6) per pulse	L <sub>s</sub> = 100 nH	T <sub>j</sub> = 25°C	_	_	_	
Eon			T <sub>j</sub> = 125°C	_	7.50	_	J
			T <sub>j</sub> = 150°C	_	7.80	_	
			T <sub>i</sub> = 25°C	_	_	_	
$t_{d(off)}$	Turn-off delay time		T <sub>j</sub> = 125°C	_	7.00	_	μs
			T <sub>i</sub> = 150°C	_	7.20	10.0	
	Fall time	V <sub>CC</sub> = 2800 V	T <sub>i</sub> = 25°C	_	_	_	
t <sub>f</sub>		I <sub>C</sub> = 1500 A	T <sub>i</sub> = 125°C	_	0.50	_	μs
		V <sub>GE</sub> = ±15 V	T <sub>i</sub> = 150°C		0.50	1.20	
E <sub>off(10%)</sub>	Turn-off switching energy (Note 5) per pulse	$R_{G(off)} = 30 \Omega$	T <sub>i</sub> = 25°C	_	_	_	
		L <sub>s</sub> = 100 nH	T <sub>j</sub> = 125°C	_	5.10	_ J	J
		Inductive load	T <sub>j</sub> = 150°C	_	5.50	_	
	T (Note 6)		T <sub>i</sub> = 25°C	_	_	_	
E <sub>off</sub>	Turn-off switching energy (Note 6)		T <sub>j</sub> = 125°C		5.50	_	J
511	per pulse		T <sub>i</sub> = 150°C	_	5.90	_	

### < High Voltage Insulated Gate Bipolar Transistor : HVIGBT >

### CM1500HC-90XA

### HIGH POWER SWITCHING USE INSULATED TYPE

#### **ELECTRICAL CHARACTERISTICS (continuation)**

Cumbal	ltom		Conditions		Limits			Unit
Symbol	Item				Min	Тур	Max	Unit
		1 4500 A (Note 4)	-	T <sub>j</sub> = 25°C		2.10	_	
$V_{EC}$	Emitter-collector voltage (Note:			T <sub>i</sub> = 125°C	_	2.50		V
	_	V <sub>GE</sub> = 0 V		T <sub>j</sub> = 150°C	_	2.50	3.00	
			-	T <sub>i</sub> = 25°C	_	_	_	
t <sub>rr</sub>	Reverse recovery time (Note	)	-	T <sub>j</sub> = 125°C	_	1.55	_	μs
			-	T <sub>j</sub> = 150°C		1.60	_	
			-	T <sub>j</sub> = 25°C		_	_	
Irr	Reverse recovery current (Note	2)	-	T <sub>j</sub> = 125°C	_	2100	_	Α
			-	T <sub>j</sub> = 150°C		2100	_	
		V <sub>CC</sub> = 2800 V	T <sub>j</sub> = 25°C	_	_	_		
Q <sub>rr(10%)</sub>	Reverse recovery charge (Note 2	<sup>7)</sup> I <sub>E</sub> = 1500 A	-	T <sub>i</sub> = 125°C	-	2750	_	μC
		V <sub>GE</sub> = ±15 V	-	T <sub>j</sub> = 150°C		2900	_	
		$R_{G(on)} = 2.4 \Omega$	-	T <sub>j</sub> = 25°C	_	_	_	
$Q_{rr}$	Reverse recovery charge (Note 2	5) L <sub>s</sub> = 100 nH	-	T <sub>i</sub> = 125°C	-	2850	_	μC
		Inductive load	-	T <sub>j</sub> = 150°C		3000	_	
	Reverse recovery energy (Note 2, 5) per pulse		-	T <sub>j</sub> = 25°C	_	_	_	
E <sub>rec(10%)</sub>			_	T <sub>j</sub> = 125°C	_	4.10	_	J
			-	T <sub>j</sub> = 150°C	_	4.50	_	
E <sub>rec</sub>	Reverse recovery energy (Note 2, 6) per pulse	,	-	T <sub>j</sub> = 25°C	_	_	_	
			[-	T <sub>j</sub> = 125°C	_	4.40		J
			-	T <sub>j</sub> = 150°C	_	4.80	_	

#### THERMAL CHARACTERISTICS

Symbol	Item	Conditions	Limits			l lmi4
			Min	Тур	Max	Unit
$R_{th(j-c)Q}$	Thermal resistance	Junction to Case, IGBT part	-	-	8.5	K/kW
$R_{th(j-c)D}$	Thermal resistance	Junction to Case, FWDi part	-	-	13.0	K/kW
R <sub>th(c-s)</sub>	Contact thermal resistance	Case to heat sink $\lambda_{grease}$ = 1W/m·K, $D_{(c-s)}$ = 80 $\mu$ m		5.0	_	K/kW

#### **MECHANICAL CHARACTERISTICS**

Cumbal	Item	Conditions	Limits			l lmi4
Symbol		Conditions		Тур	Max	Unit
$M_t$		M8 : Main terminals screw	7.0		19.0	N·m
Ms	Mounting torque	M6 : Mounting screw	3.0	_	6.0	N·m
Mt		M4 : Auxiliary terminals screw (Note 8)	1.0	_	3.0	N·m
m	Mass		_	1.2	_	kg
CTI	Comparative tracking index		600	_		_
da	Clearance		19.5	_	_	mm
d <sub>s</sub>	Creepage distance		32.0	_	_	mm
L <sub>P CE</sub>	Parasitic stray inductance		_	8.0	1	nH
R <sub>CC'+EE'</sub>	Internal lead resistance	T <sub>c</sub> = 25 °C	_	0.09	_	mΩ

Note1. Pulse width and repetition rate should be such that junction temperature (T<sub>j</sub>) does not exceed T<sub>jopmax</sub> rating.

Note2. The symbols represent characteristics of the anti-parallel, emitter to collector free-wheel diode (FWD<sub>i</sub>).

Note3. Junction temperature (T<sub>j</sub>) should not exceed T<sub>jmax</sub> rating (150°C).

Note4. Pulse width and repetition rate should be such as to cause negligible temperature rise.

Note5. The integration range of switching energies is from  $10\%V_{CE}$  to  $10\%I_{C}(10\%I_{E})$ .

Note6. Definition of all items is according to IEC 60747, unless otherwise specified.

Note7. The integration range of reverse recovery charge is from  $I_E = 0.4$  to  $10\%I_E$ .

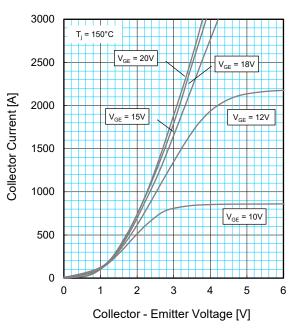
Note8. The maximum specified value is under the condition of using PCB mounted on the power module.

In case no PCB is used this maximum torque for M4 screw is 2.0 Nm.  $\,$ 

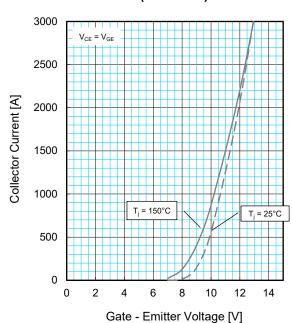
HIGH POWER SWITCHING USE INSULATED TYPE

#### **PERFORMANCE CURVES**

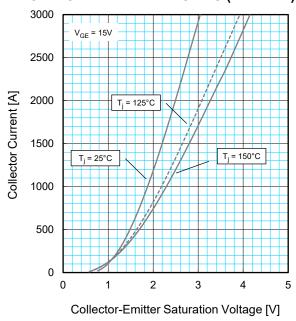
# OUTPUT CHARACTERISTICS (TYPICAL)



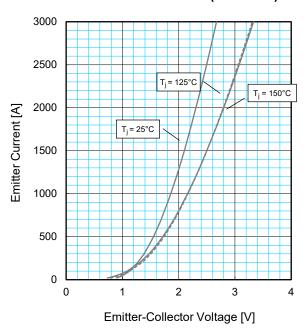
# TRANSFER CHARACTERISTICS (TYPICAL)



### COLLECTOR-EMITTER SATURATION VOLTAGE CHARACTERISTICS (TYPICAL)



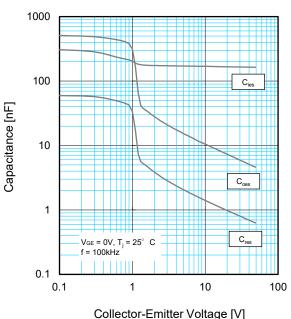
# FREE-WHEEL DIODE FORWARD CHARACTERISTICS (TYPICAL)



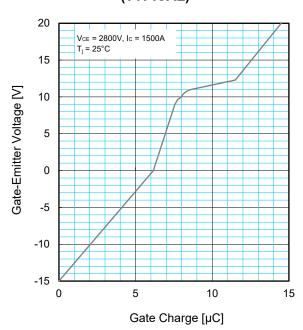
HIGH POWER SWITCHING USE INSULATED TYPE

#### **PERFORMANCE CURVES**

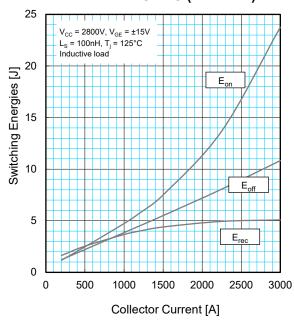
# CAPACITANCE CHARACTERISTICS (TYPICAL)



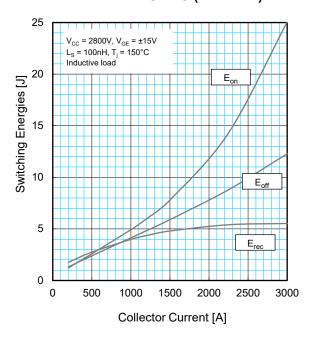
# GATE CHARGE CHARACTERISTICS (TYPICAL)



# HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



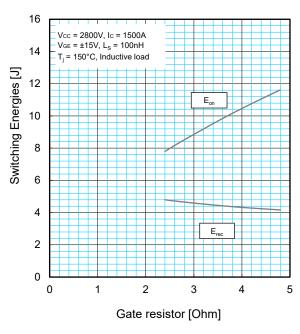
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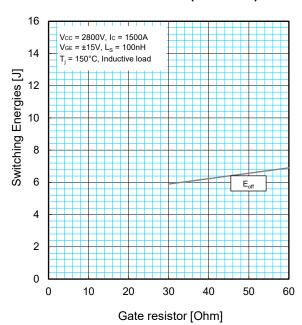
HIGH POWER SWITCHING USE INSULATED TYPE

#### **PERFORMANCE CURVES**

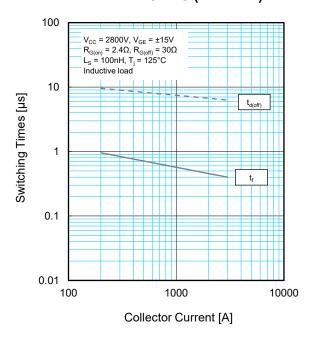
# HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



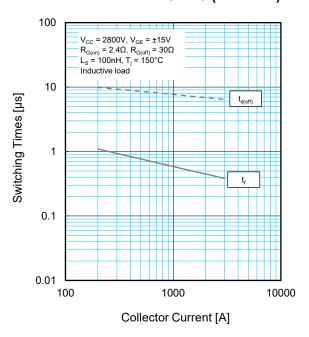
# HALF-BRIDGE SWITCHING ENERGY CHARACTERISTICS (TYPICAL)



# HALF-BRIDGE SWITCHING TIME CHARACTERISTICS (TYPICAL)



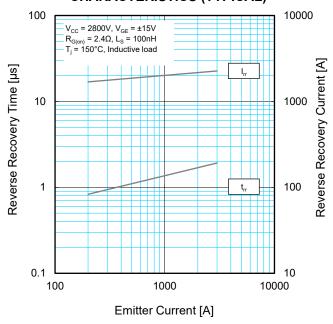
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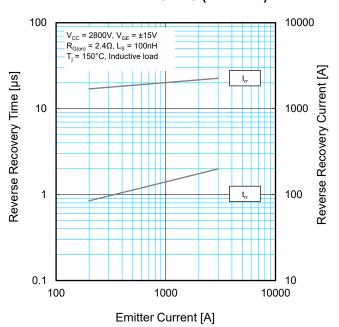
HIGH POWER SWITCHING USE INSULATED TYPE

#### **PERFORMANCE CURVES**

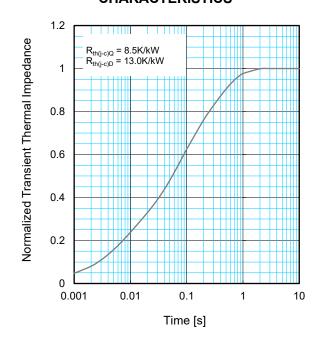
### FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



### FREE-WHEEL DIODE REVERSE RECOVERY CHARACTERISTICS (TYPICAL)



# TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS



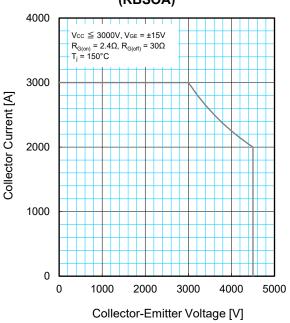
$$Z_{th(j-c)}(t) = \sum_{i=1}^{n} R_{i} \left\{ 1 - exp^{\left(-\frac{t}{\tau_{i}}\right)} \right\}$$

	1	2	3	4
R <sub>i</sub> / R <sub>th(j-c)</sub> :	0.0096	0.1893	0.4044	0.3967
τ <sub>i</sub> [sec] :	0.0001	0.0058	0.0602	0.3512

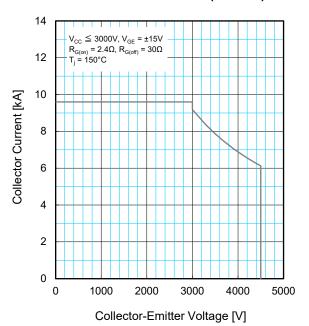
HIGH POWER SWITCHING USE INSULATED TYPE

#### **PERFORMANCE CURVES**

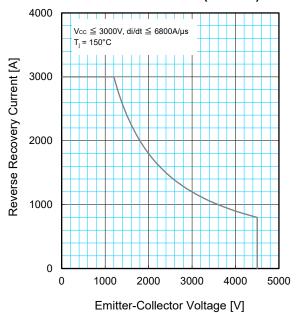
# REVERSE BIAS SAFE OPERATING AREA (RBSOA)



### SHORT CIRCUIT SAFE OPERATING AREA (SCSOA)



# FREE-WHEEL DIODE REVERSE RECOVERY SAFE OPERATING AREA (RRSOA)



< High Voltage Insulated Gate Bipolar Transistor: HVIGBT >

CM1500HC-90XA HIGH POWER SWITCHING USE INSULATED TYPE

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### CM1500HC-90XA HIGH POWER SWITCHING USE INSULATED TYPE

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